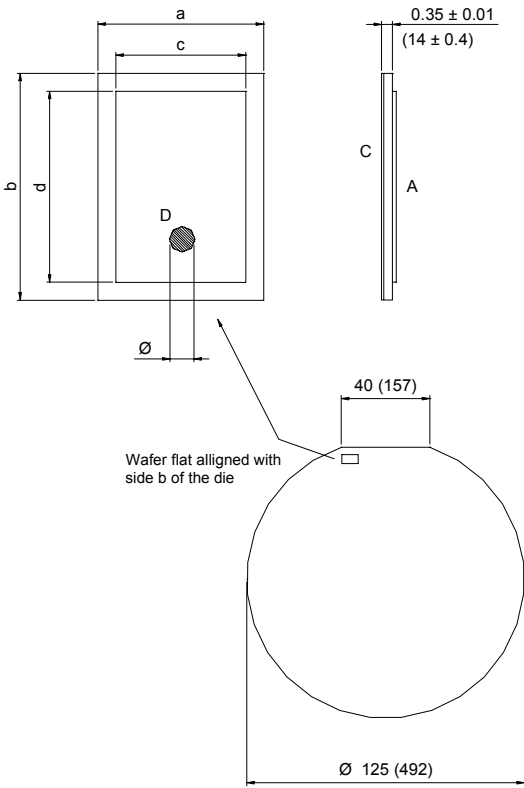


SCHOTTKY DIE 70 x 92 mils



- NOTES:
1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).
  2. CONTROLLING DIMENSION: (MILS).
  3. DIMENSIONS AND TOLERANCES:
    - $a = 1.78 + 0, - 0.01$   
(70 + 0, - 0.4)
    - $b = 2.34 + 0, - 0.01$   
(92 + 0, - 0.4)
    - $c = 1.63 + 0, - 0.01$   
(64 + 0, - 0.4)
    - $d = 2.18 + 0, - 0.01$   
(86 + 0, - 0.4)
    - $\varnothing = 0.7 \pm 0.1$   
(30  $\pm$  4)
  4. LETTER DESIGNATION:
    - A = Anode (Top Metal)
    - C = Cathode (Back Metal)
    - D = Reject Ink Dot (only on non-conforming dies)
  5. SAWING:
    - Recommended Blade
    - SEMITEC S1025 QS00 Blade
    - Sawing Street
    - 0.05 + 0, - 0.005
    - (2 + 0, - 0.2)

NOT TO SCALE

**NOTE:** 10 mils die thickness is available on specific request only.  
Contact factory for information.

## Electrical Characteristics

Device #	T <sub>J</sub> Max. (°C)	V <sub>R</sub> (V)	Typ. I <sub>R</sub> @ 25°C (μA)	Typ. I <sub>R</sub> @ 125°C (mA)	Max. V <sub>F</sub> @ I <sub>F</sub> (V)	Package Style
SC070R015x5x	125	15	n.a. contact factory			
SC070S020x5x	150	20	n.a. contact factory			
SC070S030x5x	150	30	90	38	0.55 @ 12A	DPAK(TO-252)
SC070S045x5x	150	45	70	32	0.70 @ 15A	TO-220
SC070S060x5x	150	60	n.a. contact factory			
SC070H045x5x	175	45	12	4	0.56 @ 15A	TO-220
SC070H100x5x	175	100	5	2.5	0.95 @ 12A	DPAK(TO-252)
SC070H150x5x	175	150	2	1.5	1.1 @ 10A	TO-220

## Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC070xxxxA5x	Wire Bondable	–	Al 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC070xxxxS5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

## Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
SC070xxxx5B	Inked Probed Unsawn Wafer (Wafer in Box)	2500
SC070xxxx5R	Probed Die in Tape & Reel	n.a
SC070xxxx5P	Probed Die in Waffle Pack	2500
SC070xxxx5F	Inked Probed Sawn Wafer on Film	2500

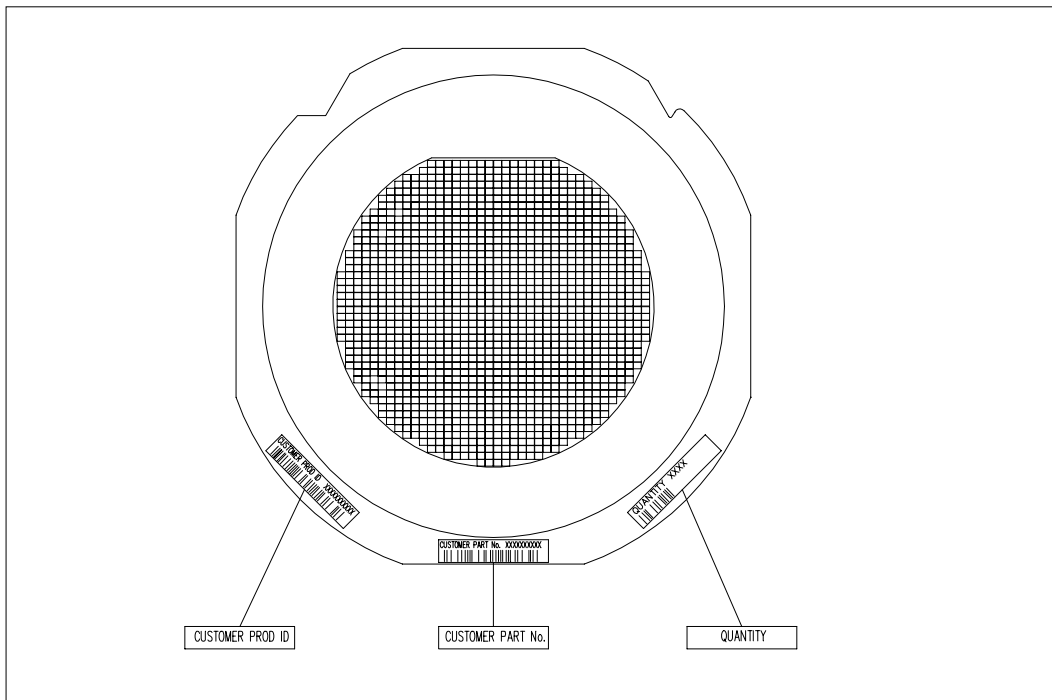
Ordering Information Table

Device Code						
SC	070	S	045	A	5	B
1	2	3	4	5	6	7

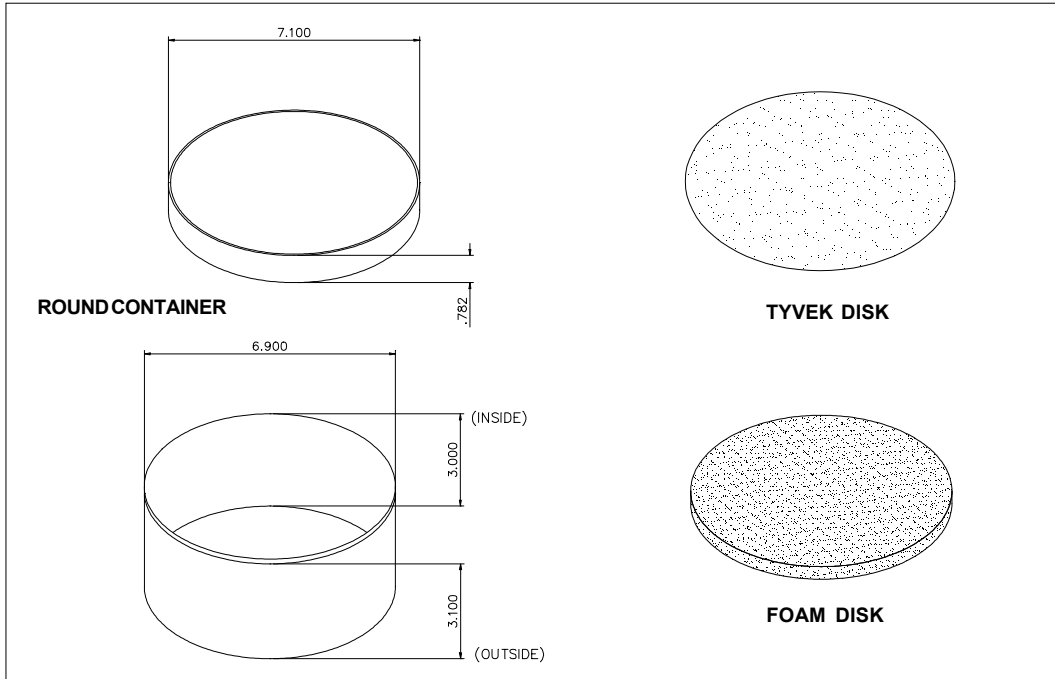
  

<ul style="list-style-type: none"> <li><b>1</b> - Schottky Die</li> <li><b>2</b> - Chip Dimension in Mils</li> <li><b>3</b> - Process (see Electrical Characteristics Table)</li> <li><b>4</b> - Voltage code: Code = <math>V_{RRM}</math></li> <li><b>5</b> - Chip surface metallization (see Mechanical Data Table)</li> <li><b>6</b> - Wafer Diameter in inches</li> <li><b>7</b> - Packaging (see Packaging Table)</li> </ul>	H = 830 Process R = OR'ing Process S = Standard Process
---	---

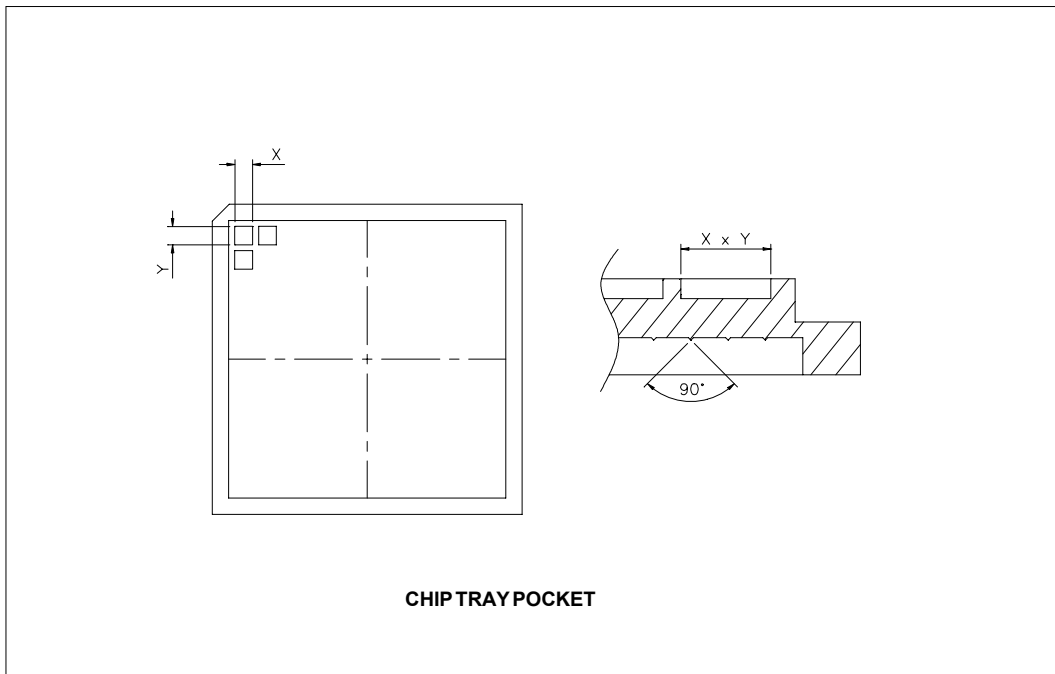
Wafer on Film



Wafer in Box



Die in Waffle Pack



International  
**IOR** Rectifier

**WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245 U.S.A. Tel: (310) 322 3331. Fax: (310) 322 3332.  
**EUROPEAN HEADQUARTERS:** Hurst Green, Oxted, Surrey RH8 9BB, U.K. Tel: ++ 44 1883 732020. Fax: ++ 44 1883 733408.  
**IR CANADA:** 15 Lincoln Court, Brampton, Markham, Ontario L6T3Z2. Tel: (905) 453 2200. Fax: (905) 475 8801.  
**IR GERMANY:** Saalburgstrasse 157, 61350 Bad Homburg. Tel: ++ 49 6172 96590. Fax: ++ 49 6172 965933.  
**IR ITALY:** Via Liguria 49, 10071 Borgaro, Torino. Tel: ++ 39 11 4510111. Fax: ++ 39 11 4510220.  
**IR FAR EAST:** K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo, Japan 171. Tel: 81 3 3983 0086.  
**IR SOUTHEAST ASIA:** 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994. Tel: ++ 65 838 4630.  
**IR TAIWAN:** 16 Fl. Suite D.207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan. Tel: 886 2 2377 9936.

<http://www.irf.com>

Fax-On-Demand: +44 1883 733420

Data and specifications subject to change without notice.